



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

*: Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-08-24
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Floriana SAN BIAGIO	Representative Title	AMS MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	DD6S*6395AAL	A	BO2A	2018-08-24
	Amount	UoM	Unit type	ST ECOPACK Grade
	54.2	mg	Each	ECOPACK® 3
Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
DSO	5x4.4x0.9	16	gull wing	
Comment	6S TSSOP 16 BODY 4.4 PITCH 0.65; MDF valid for TSV6395IPT			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
;				
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	DD65*6395AAL				5000003.0	999996.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	1.178	mg	supplier	die	Silicon (Si)	7440-21-3		1.139	mg	966893	21015
				supplier	metallization	Aluminium (Al)	7429-90-5		0.010	mg	8489	185
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	849	18
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	849	18
				supplier	Passivation	Silicon Nitride	12033-89-5		0.003	mg	2547	55
				supplier	Passivation	Silicon Oxide	7631-86-9		0.024	mg	20374	443
Leadframe	M-004 Copper and its alloys	28.088	mg	supplier	alloy	Copper (Cu)	7440-50-8		27.003	mg	961371	498210
				supplier	alloy	Nickel (Ni)	7440-02-0		0.842	mg	29977	15535
				supplier	alloy	Magnesium (Mg)	7439-95-4		0.042	mg	1495	775
				supplier	alloy	Silicon (Si)	7440-21-3		0.183	mg	6515	3376
				supplier	metallization	Nickel (Ni)	7440-02-0		0.016	mg	570	295
				supplier	metallization	Palladium (Pd)	7440-05-3		0.001	mg	36	18
Die attach	M-015 Other organic materials	0.453	mg	supplier	metallization	Gold (Au)	7440-57-5		0.001	mg	36	18
				supplier	glue	Silver (Ag)	7440-22-4		0.396	mg	874172	7306
				supplier	glue	Isobornyl Methacrylate	7534-94-3		0.023	mg	50773	424
				supplier	glue	Acrylate resin	5888-33-5		0.023	mg	50773	424
				supplier	glue	Methyl acrylate polymer	87320-05-6		0.009	mg	19868	166
				supplier	glue	Epoxycyclohexylethyltrimethoxysilane	3388-04-3		0.001	mg	2208	18
Bonding wires	M-011 Other inorganic materials	0.080	mg	supplier	glue	Tert-Butyl peroxy(2-ethyl)-hexanoate	3006-82-4		0.001	mg	2208	18
				supplier	wire	Copper (Cu)	7440-50-8		0.080	mg	1000000	1476
Encapsulation	M-015 Other organic materials	24.401	mg	supplier	mold compound	Silica, vitreous	60676-86-0		21.400	mg	877013	394834
				supplier	mold compound	Epoxy resin	85954-11-6		0.976	mg	39998	18007
				supplier	mold compound	Epoxy	29690-82-2		0.976	mg	39998	18007
				supplier	mold compound	phenol resin	Proprietary		0.732	mg	29999	13506
				supplier	mold compound	additive	Proprietary		0.244	mg	10000	4502
				supplier	mold compound	carbon black	1333-86-4		0.073	mg	2992	1347